



Product Change Notification / ALAN-03HRHE038

Date:

10-Apr-2024

Product Category:

32-Bit Microcontrollers

PCN Type:

Manufacturing Change

Notification Subject:

CCB 6777 and 6777.002 Initial Notice: Qualification of ANAP as an additional assembly location for selected ATSAM4N16C, ATSAM4N8C, ATSAM4S16C, ATSAM4S16CA, ATSAM4S2C, ATSAM4S4C, ATSAM4S4CA, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C, ATSAM4SD32C, ATSAM4S4A, ATSAM4S2A and ATSAM4N8A device families available in 100L and 48L LQFP (14x14x1.4mm and 7x7x1.4mm) packages.

Affected CPNs:

[ALAN-03HRHE038_Affected_CPN_04102024.pdf](#)

[ALAN-03HRHE038_Affected_CPN_04102024.csv](#)

Notification Text:

PCN Status:Initial Notification

PCN Type:Manufacturing Change

Microchip Parts Affected:Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change:Qualification of ANAP as an additional assembly location for selected ATSAM4N16C, ATSAM4N8C, ATSAM4S16C, ATSAM4S16CA, ATSAM4S2C, ATSAM4S4C, ATSAM4S4CA, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C, ATSAM4SD32C, ATSAM4S4A, ATSAM4S2A and ATSAM4N8A device families available in 100L and 48L LQFP (14x14x1.4mm and 7x7x1.4mm) packages.

Pre and Post Change Summary:

Applicable for ATSAM4N16C, ATSAM4N8C, ATSAM4S16C, ATSAM4S16CA, ATSAM4S2C, ATSAM4S4C, ATSAM4S4CA, ATSAM4S8C, ATSAM4SA16C, ATSAM4SD16C, ATSAM4SD32C device families in 100L LQFP:

	Pre Change		Post Change		
Assembly Site	ATX Semiconductor (Shanghai)Co. Ltd (ASSH)		ATX Semiconductor (Shanghai)Co. Ltd (ASSH)	Amkor Technology Philippine (P1/P2), INC. (ANAP)	
Wire Material	CuPdAu	CuPd	CuPdAu	CuPd	CuPdAu
Die Attach Material	2288A		2288A		3230
Molding Compound Material	CEL-9510HFL		CEL-9510HFL		G631HQ
Lead-Frame Material	C7025		C7025		C194ESH
Lead-Frame Paddle Size	240X240	180X180	240X240	180X180	256X256
Lead Lock	No		No		Yes
See Pre and Post change for Lead-Frame Comparison.					

Applicable for ATSAM4S4A, ATSAM4S2A and ATSAM4N8A device families in 48L LQFP:

	Pre Change	Post Change	
Assembly Site	ATX Semiconductor (Shanghai)Co. Ltd (ASSH)	ATX Semiconductor (Shanghai)Co. Ltd (ASSH)	Amkor Technology Philippine (P1/P2), INC. (ANAP)
Wire Material	CuPd	CuPd	CuPdAu
Die Attach Material	2288A	2288A	3230
Molding Compound Material	CEL-9510	CEL-9510	G631HQ
Lead-Frame Material	C7025	C7025	C194ESH
Lead-Frame Paddle Size	197X197	197X197	197X197
See Pre and Post change for Lead-Frame Comparison.			

Impacts to Data Sheet:None

Change Impact:None

Reason for Change:To improve on-time delivery performance by qualifying ANAP as an additional assembly site.

Change Implementation Status:In Progress

Estimated Qualification Completion Date:May 2024

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	January 2024					>	May 2024				
Workweek	1	2	3	4	5		1 8	1 9	2 0	2 1	2 2
Initial PCN Issue Date		X									
Qual Report Availability									X		
Final PCN Issue Date									X		

Method to Identify Change:Traceability code

Qualification Plan:Please open the attachments included with this PCN labeled as PCN_#_Qual_Plan.

Revision History:January 08, 2024: Issued initial notification.

April 10, 2024: Reissued the initial notification to include reference CCB 6777.002. Updated the Notification subject, Description of change and Pre and Post change summary table to include ATSAM4S4A, ATSAM4S2A and ATSAM4N8A device families. Updated the affected CPN list to include CPNs within the scope of CCB 6777.002. Updated Pre and Post Change summary to include lead frame drawing for 48L LQFP (7x7x1.4mm) package.

The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable products.

Attachments:

[PCN_ALAN-03HRHE038_Pre and Post Change Summary.pdf](#)

[PCN_ALAN-03HRHE038_Qual_Plan.pdf](#)

Please contact your local **Microchip sales office** with questions or concerns regarding this notification.

Terms and Conditions:

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

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Affected Catalog Part Numbers (CPN)

ATSAM4S4AB-AN
ATSAM4S2AB-AN
ATSAM4N8AA-AU
ATSAM4S4AA-AU
ATSAM4S2AA-AU
ATSAM4N8AA-AUR
ATSAM4S4AB-ANR
ATSAM4S2AB-ANR
ATSAM4S8CB-AN
ATSAM4S8CB-ANR
ATSAM4SD16CB-AN
ATSAM4SD16CB-ANR
ATSAM4S8CA-AN
ATSAM4S8CA-ANR
ATSAM4SD32CB-AN
ATSAM4SD32CB-ANR
ATSAM4SD32CA-AU
ATSAM4SD32CA-AUR
ATSAM4S16CB-AN
ATSAM4S16CB-ANR
ATSAM4S2CB-AN
ATSAM4S2CB-ANR
ATSAM4S16CA-AN
ATSAM4S16CA-ANR
ATSAM4S16CA-AU
ATSAM4S16CA-AUR
ATSAM4SA16CA-AU
ATSAM4SA16CA-AUR
ATSAM4SA16CB-AN
ATSAM4SA16CB-ANR
ATSAM4SD16CA-AU
ATSAM4SD16CA-AUR
ATSAM4SD16CB-AU
ATSAM4N16CA-AU
ATSAM4N16CA-AUR
ATSAM4S8CA-AU
ATSAM4S8CA-AUR
ATSAM4S4CA-AU
ATSAM4S4CA-AUR
ATSAM4S4CB-AN
ATSAM4S4CB-ANR
ATSAM4N8CA-AU
ATSAM4N8CA-AUR
ATSAM4S2CA-AU